

 <p><b>LIST OF REFERENCES CITED BY APPLICANT</b>  <small>(Use several sheets if necessary)</small></p>					ATTY. DOCKET NO 11042-005	APPLICATION NO. 10/081,768	
					APPLICANT Chen et al.		
					FILING DATE February 22, 2002	GROUP 1762	
<b>U.S. PATENT DOCUMENTS</b>							
*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
	AA						
	AB						
	AC						
	AD						
	AE						
<b>FOREIGN PATENT DOCUMENTS</b>							
		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION
	AF						YES      NO
	AG						
	AH						
	AI						
	AJ						
<b>OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, Etc.)</b>							
7	AK	Boonekamp et al., Adsorption of Nanometer-Sized Palladium Particles on Si(100) Surfaces, 10 Langmuir 4089-4094 (American Chemical Society, 1994).					
7	AL	Hidber et al., Microcontact Printing of Palladium Colloids: Micron-Scale Patterning by Electroless Deposition of Copper, 12 Langmuir 1375-80 (American Chemical Society, 1996).					
7	AM	Hidber et al., New Strategy for Controlling the Size and Shape of Metallic Features Formed by Electroless Deposition of Copper: Microcontact Printing of Catalysts on Oriented Polymers, Followed by Thermal Shrinkage, 12 Langmuir 5209-5215 (American Chemical Society, 1996).					
EXAMINER <i>Nichal Bar</i>				DATE CONSIDERED <i>12/29/03</i>			
<small>*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.</small>							